

# LTM4612 133LD 15.00mm X 15.00mm X 2.82mm (TABLE OF MATERIAL DECLARATION)

*The LTM4612 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2205	Barium Compounds	7727-43-7	0.00331	1.500
				Filler Substances (Silica Crystalline)	73776-74-4	0.08801	39.915
				Copper Metal	7631-86-9	0.12348	56.000
				Copper Compounds	7440-50-8	0.00004	0.018
				Ecotoxic substances	1328-53-6	0.00000	0.000
				Gold metal or alloy	7439-92-1	0.00101	0.460
				Nickel	7440-57-5	0.00463	2.100
				Zinc	7440-02-0	0.00002	0.007
2	Solder Paste	Alloy	0.0215	Sn	7440-66-6	0.02043	95.000
				Sb	7440-31-5	0.00108	5.000
3	Passive/Active Components		0.4710	Iron Powder (Fe)	7440-36-0	0.3541	75.18
				Copper (Cu)	7439-89-6	0.0930	19.75
				Nickel (Ni)	7440-50-8	0.0029	0.61
				Tin (Sn)	7440-02-0	0.0034	0.73
				Ceramic (Ba) Compounds	7440-31-5	0.0175	3.72
4	Active Ics	Silicon	0.0025	Silicon	12047-27-7	0.00251	100.000
5	Wire	Gold	0.0250	Au	7440-21-3	0.02500	99.990
6	Encapsulation	Epoxy Resin	1.0150	Fused Silica	60676-86-0	0.78358	77.200
				Epoxy Resin	non-disclosure	0.09034	8.900
				Phenol Resin	non-disclosure	0.09034	8.900
				Crytalline Silica	14808-60-7	0.03045	3.000
				Carbon Black	1333-86-4	0.00508	0.500
				Metal Hydroxide	non-disclosure	0.01523	1.500
Total Package Weight			1.7555				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts